The product information in this catalog is for reference only. Please request the Engineering Drawing for the most current and accurate design information.



## **IT2** Series



### Features

- **1. High-speed transmission** Differential impedance: 100Ω +/- 10% (Tr. 70 ps)
- 2. Contact reliability

Hirose's unique double contact point on each of the contacts assures highly reliable electrical and mechanical performance.

3. Self-alignment

Our unique 3-piece modular design together with large tolerances in the X and Y axis allows mating of several connectors mounted on the same PCB.

4. Low insertion / withdrawal forces

The unique contact configuration assures insertion force of 75 N max.

5. Customized Board-to-Board distance

Transmission module can be designed to accommodate distance of 15 to 50 mm between parallel boards.

### Applications

Routers, servers, base stations, communication equipment and other applications requiring high density and high speed connections between parallel boards.











**HS** A311

#### The product information in this catalog is for reference only. Please request the Engineering Drawing for the most current and accurate design information. IT2 Series High Speed, Parallel Board-to-Board (Stacking) Connector 380 contacts, Ball-Grid array termination

# ■Production Specifications

	Current rating	0.5A	Operating temperature range	-55°C to +85°C (Note 1)	Storage temperature range	-10℃ to +60℃ (Note 2)	
Ratings	Current voltage	50V AC	Operating humidity range	Relative humidity 95% (No condensation)	Storage humidity range	40% to 70% (Note 2)	
Item	Specification			Conditions			
1. Insulation resistance	100 MΩ min.			100V DC			
2. Withstanding voltage				150V AC / one minute			
3. Contact resistance	50 mΩ max. (* Including conductor resistance.)			100 mA (Corresponding connector: IT2-380P-15H)			
4. Vibration	No electrical discontinuity of 1 $\mu$ s or more. No damage, cracks, or parts dislocation.			Frequency: 10 to 55 Hz, single amplitude of 0.75mm, 10 cycle in each of the 3 directions.			
5. Shock	No electrical discontinuity of 1 $\mu$ s. min. No damage, cracks, or parts dislocation.			Acceleration of 490 m/s <sup>2</sup> , 11 ms duration, sine half-wave waveform, 3 cycles in each of the 3 axis			
6. Humidity	Contact resistance: 20 mΩ max.			96 hours at 40℃±2℃ and humidity of 90% to 95%			
7. Temperature cycle	Insulation resistance: $100 \text{ M}\Omega$ min. No damage, cracks, or parts dislocation.			Temperature: $-55^{\circ}$ C → $+15^{\circ}$ C to $+35^{\circ}$ C → $+85^{\circ}$ C → $+15^{\circ}$ C to $+35^{\circ}$ C Duration: $30 \rightarrow 5$ max. $\rightarrow 30 \rightarrow 5$ max. (Minutes) 5 cycles			
8. Durability (insertion/ withdrawal)	Contact resistance: 20 mΩ max. Insulation resistance: 100 MΩ min. No damage, cracks, or parts dislocation.			20 cycles			
9. Resistance to soldering heat	No deformation of components affecting performance.			Reflow: At the recommended temperature profile (Peak temperature: 250°C max.) Detailed solder profile can be requested.			

Note1: Includes temperature rise caused by current flow.

Note2: The term "storage" refers to products stored for long period of time prior to mounting and use. Operating Temperature Range and Humidity range covers non- conducting condition of installed connectors in storage, shipment or during transportation.

Note3: Information contained in this catalog represents general requirements for this Series. Contact us for the drawings and specifications for a specific part number shown.

### Materials/Finish

#### Receptacle

Part	Material	Finish	Remarks
Insulator	LCP	Color: Black	UL94V-0
Contacts	Phosphor bronze	Contact area: Gold plated	
Metal fitting	Phosphor bronze	Tin plated	

#### Transmission module

Part	Material	Finish	Remarks
Insulator	PBT	Color: Black/gray	UL94V-0
Board	FR-4	Contact area: Gold plated	

Note: Lead free products

### Ordering information

#### Receptacles



#### Transmission module

IT2	-	380	Ρ	*	-	15H
0		2	3	6		6

<ol> <li>Series name</li> </ol>	: IT2
2 Number of conta	cts : 380
Connector	S : Receptacle P : Transmission module
BGA Ball grid allay (Let Ball grid allay)	ead free)
<ul> <li>Transmission</li> <li>S : Standard</li> <li>M : Customized</li> </ul>	
<ul> <li>Board to board d</li> <li>15H : 15mm</li> <li>17H : 17mm</li> </ul>	
20H : 20mm 25H : 25mm	35H : 35mm

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# Recommend Temperature Profile

### **•**Using Lead-free Solder Paste



Solder composition: Paste, 96.5% Sn/3.0% Ag/0.5% Cu

# ■Recomonded spacer Hight

The two parallel boards connected by the IT2 connectors should be fastened to additioal spacers between them.

Part Number	CL No.	Recomonded spacer Hight
IT2-380PS-15H	641-2151-1	15.35±0.05 mm
IT2-380PS-17H	641-2155-2	17.35±0.05 mm
IT2-380PS-20H	641-2256-0	20.35±0.05 mm
IT2-380PS-25H	641-2251-6	25.35±0.05 mm
IT2-380PS-26H	641-2255-7	26.35±0.05 mm
IT2-380PS-30H	641-2301-2	30.35±0.05 mm
IT2-380PS-35H	641-2300-0	35.35±0.05 mm
	IT2-380PS-15H IT2-380PS-17H IT2-380PS-20H IT2-380PS-25H IT2-380PS-26H IT2-380PS-30H	IT2-380PS-15H         641-2151-1           IT2-380PS-17H         641-2155-2           IT2-380PS-20H         641-2256-0           IT2-380PS-25H         641-2251-6           IT2-380PS-26H         641-2255-7           IT2-380PS-30H         641-2301-2

